

ABSTRACT

A warpage correction system includes a warpage correction device and a relay unit. The warpage correction device corrects warpage of a first molded substrate and produce a
5 second molded substrate. The relay unit is disposed between an external processing device for the warpage correction device and the warpage correction device. The processing device processes the second molded substrate. The relay unit includes a first transport mechanism configured to receive the second molded substrate from the warpage correction device and transport the received second molded substrate to the processing device.

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(Figure 1)